ULTRA·REL Ceramic Hermetic **Frequency Mixers**

MAC Series

300 MHz to 12 GHz LO Levels 4 to 17 dBm

The Big Deal

- 3-Year Guarantee
- Hermetically sealed LTCC construction
- Low-profile case, 0.06" high
- Priced for outstanding VALUE



CASE STYLE: DZ1650

MIL Screening Available Please consult Applications Dept.

Product Overview

Mini-Circuits' MAC mixers employ a unique new design and a highly repeatable, tightly controlled, automated process that delivers industry-leading reliability at a remarkably affordable price. Schottky diode quads meeting our strict specifications are bonded to a multilayer integrated LTCC substrate, and then hermetically sealed under a controlled atmosphere with gold-plated covers and eutectic AuSn solder. These passive, doublebalanced mixers are capable of meeting MIL requirements for gross leak, fine leak, thermal shock, vibration, acceleration, mechanical shock, and HTOL (The testing can be done if requested), and every MAC mixer is backed with our 3-year guarantee.

Key Features

Feature	Advantages
Low, Flat Conversion Loss	No need to compensate for variations over frequency.
Hermetically Sealed	Ideal for use anywhere long-term reliability adds bottom-line value: high moisture areas, busy production lines, high-speed distribution centers, heavy industry, outdoor settings, and unmanned facilities, as well as military applications.
Rugged LTCC/Hermetic Construction	Demonstrated reliability in harsh, physically abusive environments with high vibration, acceleration, and/or mechanical shock.
Wide Operating Temperature Range	Guaranteed performance from -55 to +125°C. MAC mixers have also passed thermal shock testing from -55 to +150°C, through 1000 cycles, 15 minutes per cycle.
Exposed Termination Ends	Our unique case design allows for easy visual inspection of side solder fillets per IPC-A-610 section 8.3.4.6, and features gold-plated terminations for excellent solderability.
Incredible Performance/Price	Game-changing affordability brings Hi-Rel hermetic mixers within the reach of commercial budgets.

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Frequency Mixer wide BAND

MAC-12G+

Level 7 (LO Power+7 dBm) 3800 to 12000 MHz

Maximum Ratings

Operating Temperature	-55°C to 125°C
Storage Temperature	-65°C to 150°C
RF Power	50 mW
IF Current	40 mA

Permanent damage may occur if any of these limits are exceeded.

Pin Connections

LO	10
RF	5
IF	3
GROUND	1,2,4,6,7,8,9

Features

- wide bandwidth, 3800 to 12000 MHz
- low conversion loss, 6.0 dB typ.
- · LTCC double balanced mixer
- aqueous washable
- · low cost
- low profile, 0.060"
- protected by US Patent 7,027,795
- 3-YEAR GUARANTEE -The Most Reliable Mixers

Applications

- satellite up and down converters
- · line of sight links
- defense radar
- defense communications
- · federal fixed service

+RoHS Compliant

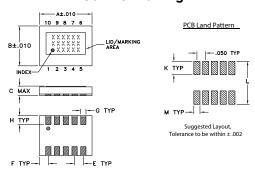
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Generic photo used for illustration purposes only

CASE STYLE: DZ1650

	Available Tape and Reel at no extra cost
Reel Size	Devices/Reel
7"	20, 50, 100, 200
13"	500,1000

Outline Drawing



Electrical Specifications at 25°C

Parameter	Condition (MHz)	Min.	Тур.	Max.	Units
Frequency Range, LO/RF			3800 - 12000		MHz
Frequency Range, IF			DC - 1800		MHz
	3800 - 6500	_	5.6	7.7	
Conversion Loss*	6500 - 9500	_	5.9	8.2	dB
	9500 - 12000	_	6.0	9.4	
	3800 - 6500	18	32	_	
LO to RF Isolation	6500 - 9500	24	38	_	dB
	9500 - 12000	17	26	_	
	3800 - 6500	8	13	_	
LO to IF Isolation	6500 - 9500	21	39	_	dB
	9500 - 12000	14	23	_	
	3800 - 6500	_	10	_	
IP3	6500 - 9500	_	7	_	dBm
	9500 - 12000	_	10	_	
RF Input Power at 1 dB Compression			+1		dBm

^{*}Conversion Loss measured at 30 MHz IF

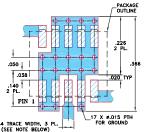
Outline Dimensions (inch)

G	F	Е	D	С	В	Α
.030	.050	.050		.060	.250	.30
0.76	1.27	1.27		1.52	6.35	7.62
wt		М	L	K	J	Н
grams		.035	.270	.085		.056
0.29		0.89	6.86	2.16		1.42

Typical Performance Data at 25°C and LO=+7dBm

Freq (N	luency (Hz)	Conversion Loss (dB)	Isolation L-R (dB)	Isolation L-I (dB)	VSWR RF Port (:1)	VSWR LO Port (:1)
RF	LO	LO +7dBm	LO +7dBm	LO +7dBm	LO +7dBm	LO +7dBm
3800.1	3830.1	5.99	31.07	10.00	1.91	2.94
4200.1	4230.1	5.27	30.81	11.42	1.75	2.96
4600.1	4630.1	5.04	26.94	12.37	1.62	3.01
5000.1	5030.1	4.87	29.19	12.85	1.74	3.04
5400.1	5430.1	6.00	28.42	14.42	2.30	3.07
5800.1	5830.1	6.41	23.66	17.11	1.62	3.11
6200.1	6230.1	5.42	27.88	23.68	1.27	3.48
6600.1	6630.1	5.21	33.16	30.31	1.16	3.58
7000.1	7030.1	6.24	35.43	35.14	1.96	3.49
7400.1	7430.1	5.63	37.74	37.00	2.13	3.20
7800.1	7830.1	5.46	38.95	37.21	2.50	2.56
8200.1	8230.1	5.90	38.84	39.61	2.83	1.83
8600.1	8630.1	6.44	34.18	43.03	3.20	1.73
9000.1	9030.1	6.57	38.49	48.65	3.02	1.88
9400.1	9430.1	5.86	34.37	40.17	2.71	2.35
9800.1	9830.1	5.58	30.24	30.03	2.37	2.72
10200.1	10230.1	5.70	30.90	19.19	1.69	2.90
10800.1	10830.1	5.58	24.14	22.91	1.18	2.38
11600.1	11630.1	6.16	21.85	28.95	1.65	1.40
12000.1	12030.1	6.38	24.79	23.67	1.96	1.59

Demo Board MCL P/N: TB-956+ Suggested PCB Layout (PL-045)

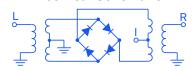


1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .020" ± .0015"; COPPER: 1/2 0Z. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED. 2. BOTTOM SIDE OF THE POB IS CONTINUOUS GROUND PLANE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

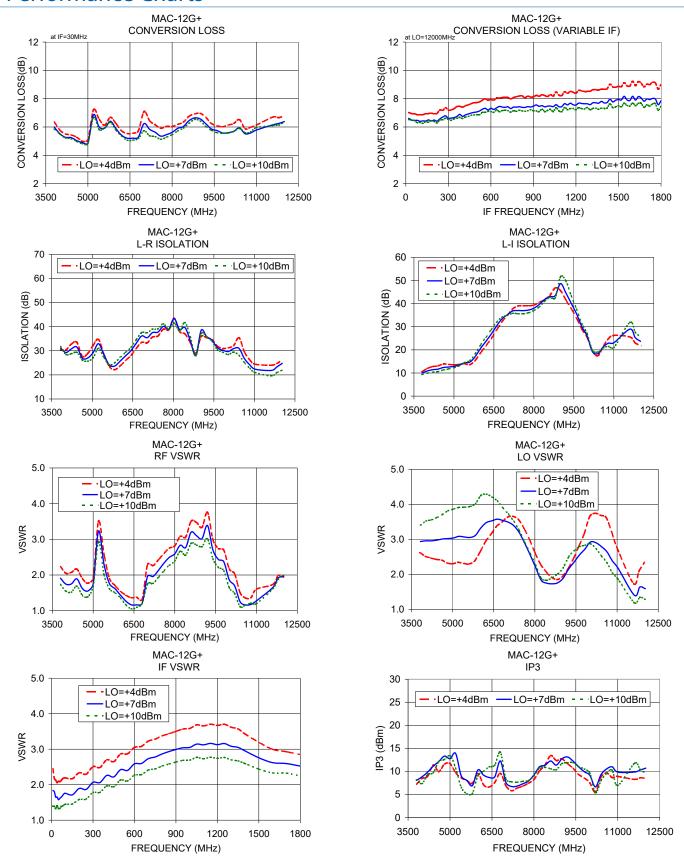
Electrical Schematic



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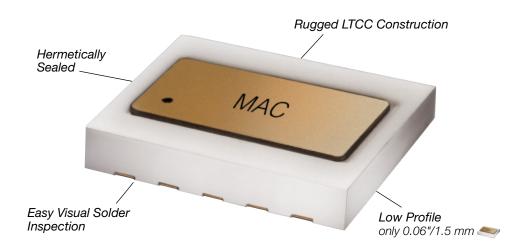


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Designed and Built for Long-Term Reliability in **HOSTILE ENVIRONMENTS**



Qualification Testing

The table below shows the initial qualification testing performed. If required, parts can be subjected to 100% screening and qualifications testing per MIL standard requirement.

Gross Leak	MIL-STD-202 Method 112, Condition D
	(100% of all MAC Mixers we ship)

Fine Leak	MIL-STD-202 Method 112,	Condition C,

Procedure IIIa

Thermal Shock MIL-STD-202 Method 107

> (-55/+100C°, 1000 cycles, 15 minutes) (-55/+150C°, 1000 cycles, 15 minutes)

Vibration MIL-STD-202 Method 204, Condition D

(10-2000Hz sine, 20g, 3 axis, 12 c.y.ea.)

Acceleration MIL-STD-883 Method 2001, Condition E

Mechanical Shock MIL-STD-202 Method 213, Condition A

HTOL MIL-STD-202 Method 108, Condition D

(1000 hours, 125°C, at rated LO level)

Multiple Reflow JESD22-B102

Bend Test JESD22-B113

Adhesion Strength Push test >10lb









All Photos courtesy of U.S. Military and NASA

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